

Figure 1

Prior Art

16

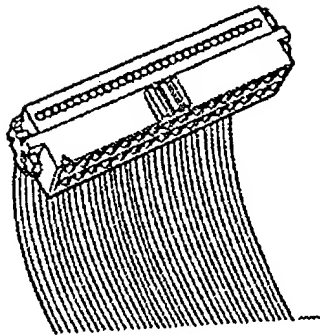


Figure 2
Prior Art

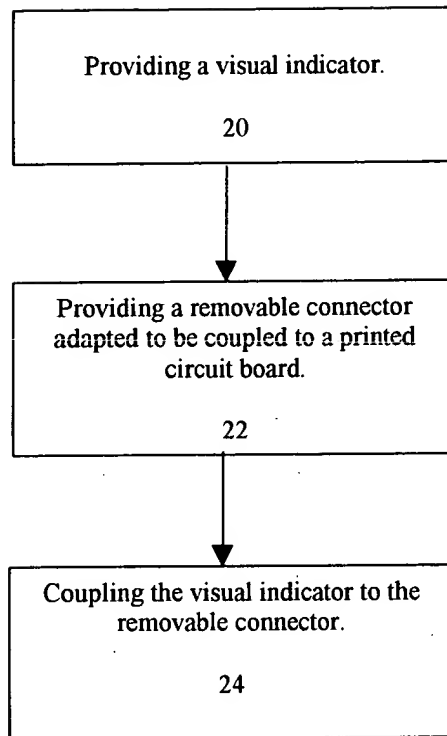
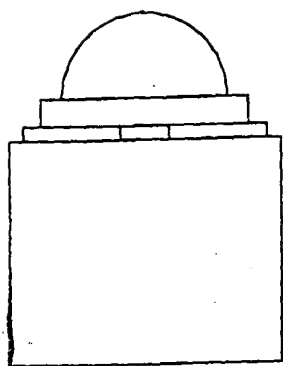
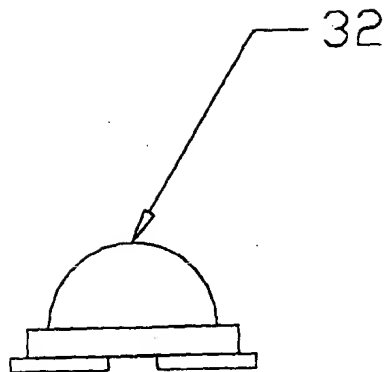


Figure 3



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Figure 4(a)



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Figure 4(b)

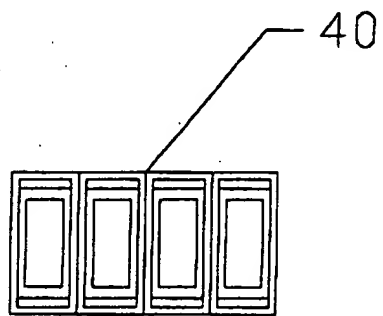


Figure 5(a). Top View

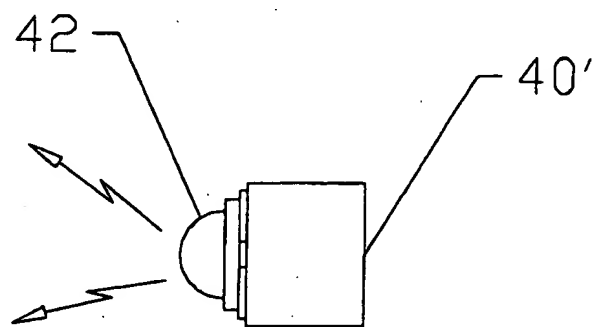


Figure 5(b). Side View

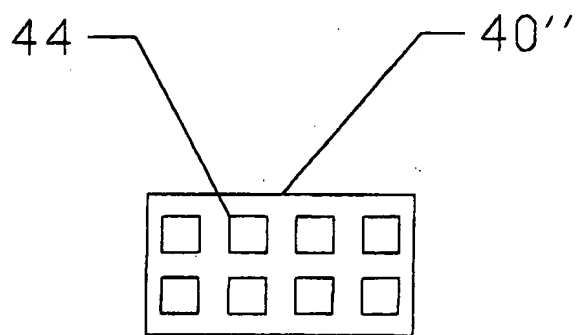


Figure 5(c). Bottom View

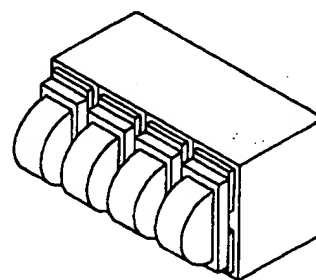


Figure 5(d). Perspective View

This diagram shows an exploded perspective view of a multi-layer printed circuit board (PCB) assembly. The assembly consists of several layers and components:

- 66, 64, 62, 60:** These labels point to the individual layers of the PCB stack, which are shown as rectangular plates with rounded corners and mounting holes.
- 74, 72, 70:** These labels point to specific components or features on the layers, which appear to be multi-pin connectors or interface modules.
- 56, 54, 52:** These labels point to circular features, likely mounting holes or vias, located on the layers.
- 50:** This label points to a separate rectangular component with a grid of small square features, possibly a microchip or a specialized connector, positioned below the main stack.

The diagram illustrates the spatial relationship and alignment of these components for assembly.

Figure 6